

# **Product Compliance Declaration**

Please see <u>www.molex.com</u> for the most up-to-date information.

Contact Information					
Name	Molex Product Compliance	E-Mail	Product.Compliance@molex.com		
Part Inform	ation				
Part Number	0015249104	Part Weight	4.082G		
Part Name	MiniFit BMI RA Hdr Tin V-0 10Ckt				

## **Product Composition**

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)	
MiniFit BMI RA Hdr Tin V-0 10Ckt	Assembly		100	4.082	
10CKT BLIND MATE HOUSING 4240410B1	Component		43.7776	1.787	
PA66 UF NATURAL	Material		43.7776	1.787	
PA66	Substance		37.6487	1.53682	
Flame Retardant, ISO 1043-4 FR(30)	Substance		5.2533	0.21444	
Pentaerythritol tetrakis(3-(3,5-di-tert-butyl-4- hydroxyphenyl)propionate)	Substance	6683-19-8	0.4378	0.01787	
Calcium distearate	Substance	1592-23-0	0.4378	0.01787	
.720 X .042 Sq. Bando pin 222 Matte Tin	Assembly		22.1705	0.905	
0.720 X .042 Sq Bando Pin 999	Component		21.6805	0.885	
Cartridge Brass 70% Unplated	Material		21.6805	0.885	
Copper	Substance	7440-50-8	15.1764	0.6195	
Zinc (metal)	Substance	7440-66-6	6.5042	0.2655	
Tin Plating	Material		0.3062	0.0125	

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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Tin	Substance	7440-31-5	0.3062	0.0125
Nickel Plating	Material		0.1837	0.0075
Nickel	Substance	7440-02-0	0.1837	0.007499
Further Additives	Substance	system	2E-5	8E-7
1.106 X .042 Sq Bando Pin 222 Matte Tin	Assembly		34.0519	1.39
1.106 X .042 Sq Bando Pin 999	Component		33.1945	1.355
Cartridge Brass 70% Unplated	Material		33.1945	1.355
Copper	Substance	7440-50-8	23.2362	0.9485
Zinc (metal)	Substance	7440-66-6	9.9584	0.4065
Tin Plating	Material		0.245	0.01
Tin	Substance	7440-31-5	0.245	0.01
Nickel Plating	Material		0.6124	0.025
Nickel	Substance	7440-02-0	0.6124	0.024997
Further Additives	Substance	system	6E-5	0.000003

## **ROHS** Declaration Information

Regulatory Revision 2011/65/EU

Compliance Status Compliant

#### **Contained Substances Exceeding Threshold**

None

#### Exemptions

None

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## **REACH-SVHC** Declaration Information

Regulatory Revision ED/30/2017 (7 July 2017)

## **Contained Substances Exceeding Threshold**

None

## **GADSL** Declaration Information

Regulatory Revision GADSL imported from IMDS

## **Contained Substances Exceeding Threshold**

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Nickel	Ep-Ni	*Note	997,500	Yes
Copper	Cartridge Brass 70% (CA260)	*Note	700,000	Yes
Lead	Cartridge Brass 70% (CA260)	*Note	350	Yes
Lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	150	Yes

\*Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

#### Exemptions

Part Name	Exemption
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/ cm2/week)

## **HFLH Declaration Information**

Regulatory Revision IEC 61249-2-21

#### **Contained Substances Exceeding Threshold**

None

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## **China ROHS Declaration Information**

Part Number 0015249104						
Part Name MiniFit BMI RA Hdr Tin V-0 10Ckt						
Part Information		Ha	zardous S	Substance	s	
Components	Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
MiniFit BMI RA Hdr Tin V-0 10Ckt	0	0	0	0	0	0
10CKT BLIND MATE HOUSING 4240410B1		0	0	0	0	0
.720 X .042 Sq. Bando pin 222 Matte Tin		0	0	0	0	0
0.720 X .042 Sq Bando Pin 999	0	0	0	0	0	0
1.106 X .042 Sq Bando Pin 222 Matte Tin		0	0	0	0	0
1.106 X .042 Sq Bando Pin 999	0	0	0	0	0	0

## **Process Information**

Component Plating / Surface Finish	MSn-Ni
Termination Base Alloy	Brass
Solder Alloy	N/A
Process Capability	WAVE
Maximum Exposure Time (seconds)	005
Maximum Process Temperature (C)	240
Maximum Cycles at Reflow Temperature	001
J-STD-020 Moisture Sensitivity Level	N/A

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